

JANS 2N5152L and JANS 2N5154L

RADIATION HARDENED NPN POWER SILICON TRANSISTOR Qualified per MIL-PRF-19500/544

DESCRIPTION

These RHA level 2N5152L and 2N5154L silicon transistor devices are military Radiation Hardness Assurance qualified up to a JANSF level for high-reliability applications. Microsemi also offers numerous other products to meet higher and lower power voltage regulation applications.

Important: For the latest information, visit our website http://www.microsemi.com.

FEATURES

- JEDEC registered 2N5152 and 2N5154.
- JANS RHA qualifications are available per MIL-PRF-19500/544.

APPLICATIONS / BENEFITS

- High frequency operation.
- Lightweight.
- High-speed power-switching applications.
- High-reliability applications.

MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	$T_{\rm J}$ and $T_{\rm STG}$	-65 to +200	°C
Thermal Resistance Junction-to-Ambient	R _{ØJA}	175	°C/W
Thermal Resistance Junction-to-Case	R _{eJC}	10	°C/W
Reverse Pulse Energy ⁽¹⁾		15	mJ
Collector Current (dc)	Ι _C	2	А
Collector to base voltage (static), emitter open	V _{CBO}	100	V
Collector to emitter voltage (static) base open	V _{CEO}	80	V
Emitter to base voltage (static) collector open	V _{EBO}	5.5	V
Steady-State Power Dissipation @ T _A = +25 °C	PD	1	W
Steady-State Power Dissipation @ T _C = +25 °C	PD	10	W

Notes: 1. This rating is based on the capability of the transistors to operate safely in the unclamped inductive load energy test circuit.

<u>Qualified Levels</u>: JANSM, JANSD, JANSP, JANSL, JANSR, JANSF



TO-5 Package

Also available in:

TO-39 Package (leaded) JANS_2N5152 & JANS_2N5154

> U3 Package (surface mount) JANS_2N5152U3 & JANS_2N5154U3

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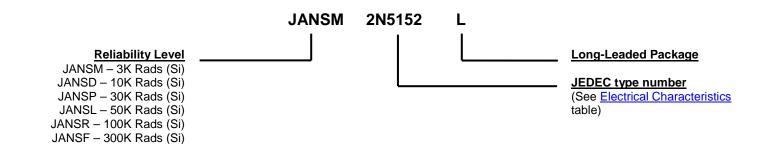
MECHANICAL and PACKAGING

- CASE: Hermetically sealed, kovar base, nickel cap.
- TERMINALS: Leads are kovar, nickel plated, and finish is solder dip (Sn63/Pb37).
- MARKING: Part number, date code, manufacturer's ID.
- POLARITY: NPN (see package outline).
- WEIGHT: Approximately 1.14 grams.

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• See Package Dimensions on last page.

PART NOMENCLATURE



	SYMBOLS & DEFINITIONS				
Symbol	Definition				
C _{obo}	Common-base open-circuit output capacitance				
I _{CEO}	Collector cutoff current, base open				
I _{CEX}	Collector cutoff current, circuit between base and emitter				
I _{EBO}	Emitter cutoff current, collector open				
h _{FE}	Common-emitter static forward current transfer ratio				
V _{CEO}	Collector-emitter voltage, base open				
V _{CBO}	Collector-emitter voltage, emitter open				
V _{EBO}	Emitter-base voltage, collector open				



ELECTRICAL CHARACTERISTICS @ $T_A = +25$ °C unless otherwise noted.

OFF CHARACTERISTICS

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	80		
$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 0$	(BI()CEO			V
Emitter-Base Cutoff Current			1.0	μA
$V_{EB} = 4.0 \text{ V}, \text{ I}_{C} = 0$	I _{EBO}		1.0	mA
$V_{EB} = 5.5 \text{ V}, \text{ I}_{C} = 0$			1.0	ША
Collector-Emitter Cutoff Current			1.0	
$V_{CE} = 60 \text{ V}, \text{ V}_{BE} = 0$	I _{CES}		1.0	μA
$V_{CE} = 100 \text{ V}, \text{ V}_{BE} = 0$			1.0	mA
Collector-Emitter Cutoff Current			50	
$V_{CE} = 40 \text{ V}, \text{ I}_{B} = 0$	ICEO		50	μA

ON CHARACTERISTICS

Parameters / Test Conditions		Symbol	Min.	Max.	Unit
Forward-Current Transfer Ratio					
$I_{C} = 50 \text{ mA}, V_{CE} = 5 \text{ V}$	2N5152L		20		
	2N5154L		50		
$I_{C} = 2.5 \text{ A}, V_{CE} = 5 \text{ V}$	2N5152L	h _{FE}	30	90	
	2N5154L		70	200	
$I_{C} = 5A, V_{CE} = 5V$	2N5152L		20		
	2N5154L		40		
Collector-Emitter Saturation Voltage				0.75	
I _C = 2.5 A, I _B = 250 mA		V _{CE(sat)}		1.5	V
I _C = 5.0 A, I _B = 500 mA				1.5	
Base-Emitter Voltage Non-Saturation		V _{BE}		1.45	V
$I_{C} = 2.5 \text{ A}, V_{CE} = 5 \text{ V}$		V BE		1.45	v
Base-Emitter Saturation Voltage				1.45	
I _C = 2.5 A, I _B = 250 mA		V _{BE(sat)}		2.2	V
$I_{\rm C} = 5.0 \text{ A}, I_{\rm B} = 500 \text{ mA}$				2.2	

DYNAMIC CHARACTERISTICS

Parameters / Test Conditions	Symbol	Min.	Max.	Unit	
Magnitude of Common Emitter Small-Signal Short-					
Circuit Forward Current Transfer Ratio 2N5152L		h _{fe}	6		
$I_{C} = 500 \text{ mA}, V_{CE} = 5 \text{ V}, \text{ f} = 10 \text{ MHz}$	2N5154L		7		
Small-signal short Circuit Forward-Curre	ent				
Transfer Ratio	2N5152L	h _{fe}	20		
$I_{C} = 100 \text{ mA}, V_{CE} = 5 \text{ V}, f = 1 \text{ KHz}$	2N5154L		50		
Output Capacitance		C _{obo}		250	pF
$V_{CB} = 10 \text{ V}, \text{ I}_{E} = 0, \text{ f} = 1.0 \text{ MHz}$		Cobo		200	Ы



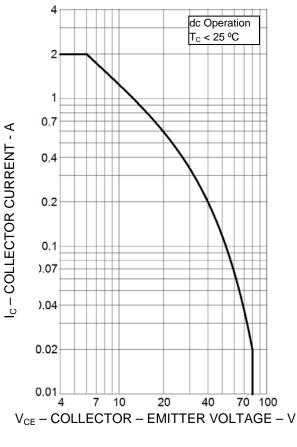
ELECTRICAL CHARACTERISTICS @ $T_A = +25$ °C unless otherwise noted. (continued)

SWITCHING CHARACTERISTICS

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Turn-On Time $I_{C} = 5 \text{ A}, I_{B1} = 500 \text{ mA}$	t _{on}		0.5	μs
Turn-Off Time $R_L = 6\Omega$	t _{off}		1.5	μs
Storage Time I _{B2} = -500 mA	t _S		1.4	μs
Fall Time V _{BE(OFF)} = 3.7 V	t _f		0.5	μs

SAFE OPERATING AREA (See SOA graph below and <u>MIL-STD-750, method 3053</u>)

 $\begin{array}{l} \textbf{DC Tests} \\ T_{C} = +25 \ ^{\circ}\text{C}, \ t_{P} = 1.0 \ \text{s}, \ 1 \ \text{Cycle} \\ \textbf{Test 1} \\ V_{CE} = 5.0 \ \text{V}, \ I_{C} = 2.0 \ \text{A} \\ \textbf{Test 2} \\ V_{CE} = 32 \ \text{V}, \ I_{C} = 310 \ \text{mA} \\ \textbf{Test 3} \\ V_{CE} = 80 \ \text{V}, \ I_{C} = 12.5 \ \text{mA} \end{array}$



Maximum Safe Operating Area



ELECTRICAL CHARACTERISTICS @ $T_A = +25 \text{ °C}$, unless otherwise noted (continued)

POST RADIATION ELECTRICAL CHARACTERISTICS

Parameters / Test Conditions		Symbol	Min.	Max.	Unit
Collector to Emitter Cutoff Current		I _{CEO}		100	μA
V _{CE} = 40 V		ICEO		100	μΛ
Emitter to Base Cutoff Current		I _{EBO}		2.0	μA
V _{EB} = 4 V		IEBO		2.0	μΛ
Breakdown Voltage, Collector to Emitter		V _{(BR)CEO}	80		V
I _C = 100 mA		V (BR)CEO	00		v
Collector to Emitter Cutoff Current		I _{CES}		2.0	μA
V _{CE} = 60 V		ICES		2.0	μΛ
Emitter to Base Cutoff Current		I _{EBO}		2.0	mA
V _{EB} = 5.5 V		IEBO		2.0	шл
Forward-Current Transfer Ratio ⁽¹⁾					
$I_{C} = 50 \text{ mA}, V_{CE} = 5 \text{ V}$	2N5152L		[10]		
	2N5154L		[25]		
$I_{C} = 2.5 \text{ A}, V_{CE} = 5 \text{ V}$	2N5152L	[h _{FE}]	[15]	90	
	2N5154L		[35]	200	
$I_{C} = 5 \text{ A pulsed}, V_{CE} = 5 \text{ V}$	2N5152L		[10]		
	2N5154L		[20]		
Base to Emitter voltage (non-saturated) $V_{CE} = 5 \text{ V}, I_C = 2.5 \text{ A}, \text{ pulsed}$		V_{BE}		1.45	V
Collector-Emitter Saturation Voltage					
$I_{\rm C}$ = 2.5 mA, $I_{\rm B}$ = 250 mA, pulsed		V _{CE(sat)}		0.86	V
$I_{\rm C}$ = 500 mA, $I_{\rm B}$ = 500 mA, pulsed				1.73	
Base-Emitter Saturation Voltage					
I_{C} = 2.5 A, I_{B} = 250 mA, pulsed		V _{BE(sat)}		1.67	V
$I_{\rm C} = 5$ A, $I_{\rm B} = 500$ mA, pulsed				2.53	

(1) See method 1019 of MIL-STD-750 for how to determine $[h_{FE}]$ by first calculating the delta $(1/h_{FE})$ from the preand post-radiation h_{FE} . Notice the $[h_{FE}]$ is not the same as h_{FE} and cannot be measured directly. The $[h_{FE}]$ value can never exceed the pre-radiation minimum h_{FE} that it is based upon.



GRAPHS

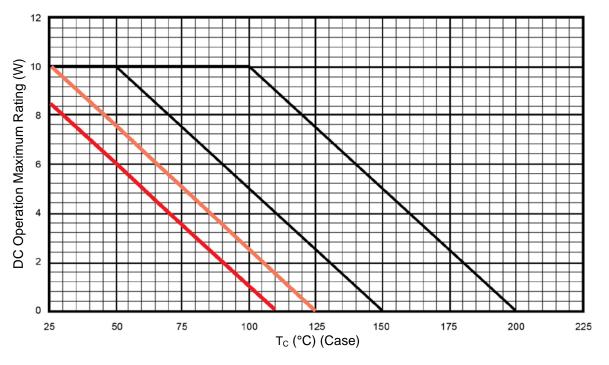


FIGURE 1 Temperature-Power Derating Curve

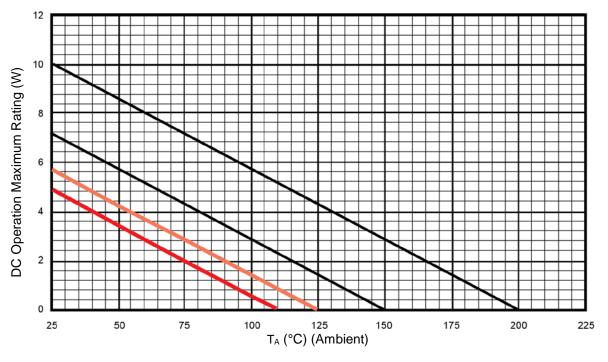
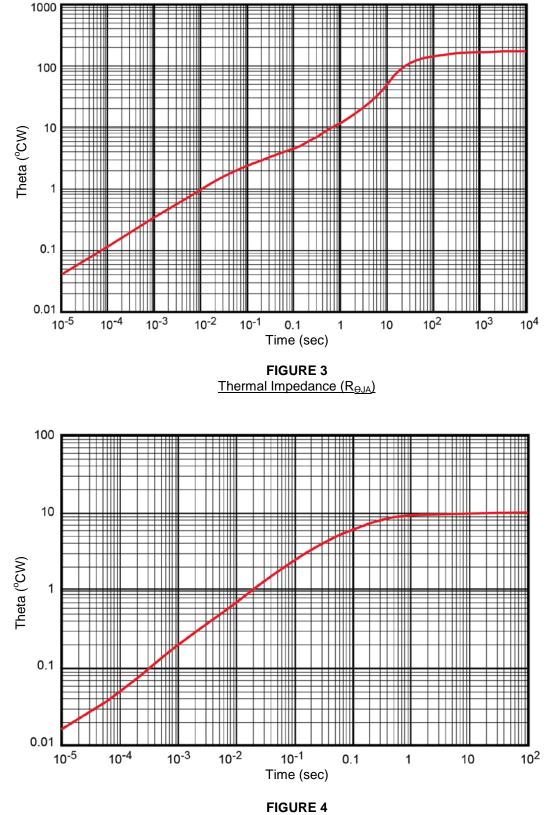


FIGURE 2 Temperature-Power Derating Curve



GRAPHS (continued)

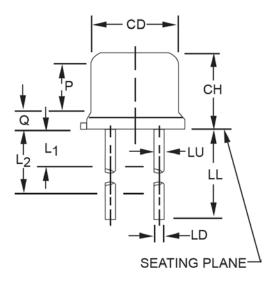


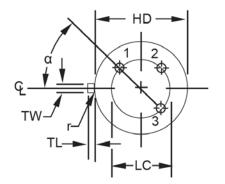
Thermal Impedance (R_{OJC})



JANS 2N5152L and JANS 2N5154L

PACKAGE DIMENSIONS





	Dimensions					
Symbol	Inch		nch Millimeters		Note	
	Min	Max	Min	Max		
CD	.305	.335	7.75	8.51	6	
СН	.240	.260	6.10	6.60		
HD	.335	.370	8.51	9.40		
LC	.200) TP	5.08	3 TP	7	
LD	.016	.019	0.41	0.48	8,9	
LL		See note 14				
LU	.016	.019	0.41	0.48	8,9	
L1		.050		1.27	8,9	
L2	.250		6.35		8,9	
Р	.100		2.54		7	
Q		.030		0.76	5	
TL	.029	.045	0.74	1.14	3,4	
TW	.028	.034	0.71	0.86	3	
r		.010		0.25	10	
α	45° TP		P 45° TP		7	

NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Beyond r (radius) maximum, TW shall be held for a minimum length of .011 (0.28 mm).
- 4. Dimension TL measured from maximum HD.
- 5. Body contour optional within zone defined by HD, CD, and Q.
- 6. CD shall not vary more than .010 inch (0.25 mm) in zone P. This zone is controlled for automatic handling.
- Leads at gauge plane .054 +.001 -.000 inch (1.37 +0.03 -0.00 mm) below seating plane shall be within .007 inch (0.18 mm) radius of true position (TP) at maximum material condition (MMC) relative to tab at MMC. The device may be measured by direct methods or by gauging procedure.
- 8. Dimension LU applies between L1 and L2. Dimension LD applies between L2 and LL minimum. Diameter is uncontrolled in and beyond LL minimum.
- 9. All three leads.
- 10. The collector shall be internally connected to the case.
- 11. Dimension r (radius) applies to both inside corners of tab.
- 12. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.
- 13. Lead 1 =emitter, lead 2 =base, lead 3 =collector.
- 14. TO-5 dimension LL = 1.5 inches (38.10 mm) min. and 1.75 inches (44.45 mm) max.

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